

### DoD Microelectronics Commons

A National Network for Defense Microelectronics Innovation

**Government-University-Industry Research Roundtable:** 

February 8, 2023

Dr. Dev Shenoy, PD Microelectronics, Director Defense Microelectronics Cross Functional Team OUSD (R&E) Microelectronics Modernization

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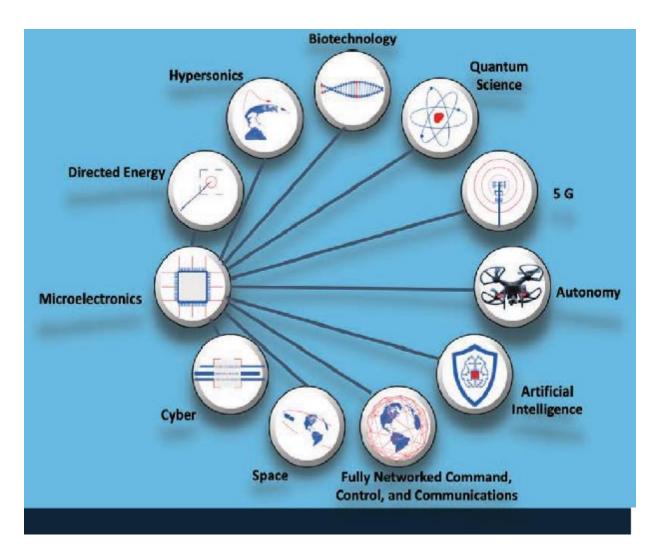


If there is any inconsistency between the material presented here and the Request for Solutions (RFS), the RFS shall take precedence.

The Microelectronics Commons RFS will be posted on <a href="www.sam.gov">www.sam.gov</a> and <a href="https://nstxl.org/opportunity/microelectronics-me-commons/">https://nstxl.org/opportunity/microelectronics-me-commons/</a>



## CRITICAL TECHNOLOGY SYNERGIES: MICROELECTRONICS







## Microelectronics a "must-win" technology for DoD

**BUILDING RESILIENT** SUPPLY CHAINS, REVITALIZING AMERICAN MANUFACTURING, AND FOSTERING BROAD-BASED **GROWTH** 

100-Day Reviews under Executive Order 14017

June 2021

INTERIM NATIONAL

SECURITY STRATEGIC GUIDANCE

Fact Sheet: 2022 National Defense Strategy

Today, the Department of Defense transmitted to Congress the classified 2022 National Def

the Nuclear Posture Review (NPR) and Missile Defense Review (MDR) in the NDS - ensuring tigh linkages between our strategy and our resources. The unclassified NDS will be forthcoming

stent with the President's Interim National Security Strategic Guidance, the classified NDS sets out how the Department of Defense will contribute to advancing and safeguarding vital U.S. national intere

U.S. Department of Defense

- 1. Defending the homeland, paced to the growing multi-domain threat posed by the PR
- 2. Deterring strategic attacks against the United States, Allies, and partne
- Deterring aggression, while being prepared to prevail in conflict when necessary, prioritizing the PRC challenge in the Indo-Pacific, then the Russia challenge in Europe 4. Building a resilient Joint Force and defense ecosystem.

Russia poses acute threats, as illustrated by its brutal and unprovoked invasion of Ukraine. We will collaborate with our NATO Allies and partners to reinforce robust deterrence in the face of Russian

The Department will remain capable of managing other persistent threats, including those from North

Changes in global climate and other dangerous transboundary threats, including pandemics, are transforming the context in which the Department operates. We will adapt to these challenges, which increasingly place pressure on the Joint Force and the systems that support it.

ight through, and recover quickly from disruption.

"Semiconductors are essential to national security. . . . They are fundamental to the operation of virtually every military system, including communications and navigations systems and complex weapons systems such as those found in the F-35 Joint Strike Fighter."

> "Semiconductors are key to the "must-win" technologies of the future, including artificial intelligence and 5G, which will be essential to achieving the goal of a "dynamic," inclusive and innovative national economy" identified as a critical American advantage in the March 2021 Interim National Security Strategic Guidance.

> > "Building enduring advantages . . . getting the technology we need more quickly, and making investments in the extraordinary people of the Department, who remain our most valuable resource."



# **DoD Addressing CHIPS Requirements for U.S. Microelectronics Ecosystem**

Initiative	Торіс	CHIPS Ref Language	CHIPS SEC.
Public Private Partnerships	<ul> <li>Partnerships to address DoD needs</li> </ul>	<ul> <li>ensure development, production, acquisition, and sustainment of measurably secure microelectronics,</li> <li>advancement of RF/OE and RADHARD technologies,</li> <li>identification of work force and infrastructure resource requirements, designation of officials for maintenance of capabilities</li> </ul>	- 9903. (a) 6A
NAS	- PPP Study	<ul> <li>Agreement with the National Academies of Science, Engineering, and Medicine to undertake a study to make recommendations and provide policy options for optimal public-private partnerships and partnership activities</li> </ul>	- 9903. (a) 6C
ME Commons	- PPP for Lab-To- Fab onshore Prototyping	<ul> <li>enable the laboratory-to-fabrication transition of microelectronics innovations</li> <li>global leadership in microelectronics of the United States</li> <li>cost effective exploration of new materials, devices, and architectures, and prototyping</li> <li>accelerate the transition of new technologies to domestic microelectronics manufacturers</li> <li>accomplishing the purposes of the National Network for Microelectronics Research and Development</li> </ul>	- 9903. (b) 1A - 9903. (b) 1B - 9903. (b) 2A - 9903. (b) 2B - 9903. (b) 2C

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### CHIPS Funded Study on Semiconductor Public-Private Partnership Models

Initiated: Congressionally Required NAS Study on 26 September

NATIONAL ACADEMIES Medicine

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### Global Microelectronics: Models for the Department of **Defense in Semiconductor Public-Private Partnerships**







About

Description Sponsors

Contact

This study will identify, explore, and assess public-private partnership models that have the potential to enable assured access for the production of semiconductors in the United States.

Description

Statement of Task: A National Academies of Sciences, Engineering, and Medicine-appointed ad hoc committee will identify, explore, and assess public-private partnership models that have the potential to enable assured access for the production of semiconductors in the United States. The committee will produce a consensus report that addresses the following questions.

Provide feedback on this project

#### DIVISIONS

Division on Engineering and Physical Sciences

Policy and Global Affairs

UNITS



## Lab-to-Fab Transition of Microelectronics Technologies



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Research Universities, Start-ups have facilities for <u>Lab</u> prototyping but face barriers to demonstrating manufacturability in a Fab.

Core Facilities or Foundries/Fabs provide access to early stage Fab prototyping.

Microelectronics Commons aims to enable lab-to-fab prototyping— evolve microelectronics laboratory prototyping to foundry/fab prototyping — in domestic facilities.



## The Microelectronics Commons: Innovation from Lab-to-Fab

### **Innovation Barriers**

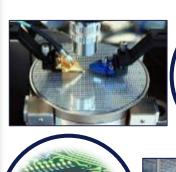
Lack of access to existing fabs for lab-to-fab prototyping

High capital costs for process and metrology tooling to support manufacturing of microelectronics technologies

High Intellectual Property (IP) and Electronic Design Automation (EDA) design license costs

Lack of domestic access to chip carriers, and packaging materials to support integration of electronics

Lack of workforce talent and expertise to support technology transition











### **End State**

**Sustained partnerships** between emerging technology sources, manufacturing facilities, and interagency partners

Rapid transition of early-stage microelectronics research to proven technology in domestic foundries

Expand **domestic** microelectronics fabrication capability

Enhance microelectronics **education** to bolster the microelectronics engineering workforce

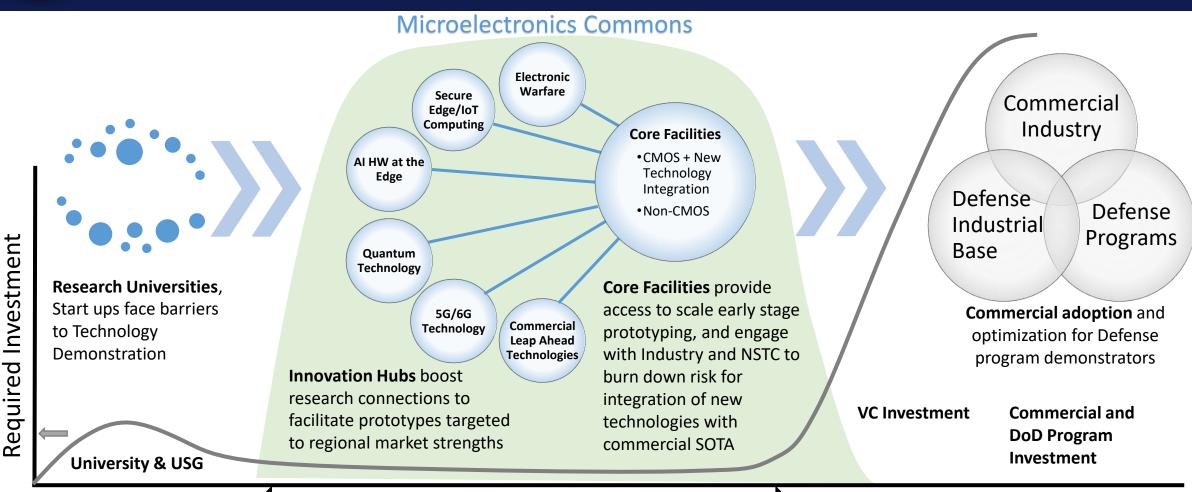
Develop a **pipeline of talent** to bolster local semiconductor economies and grow the domestic semiconductor workforce



# Microelectronics Commons Addresses the Valley of Death



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Proof of Concept

Prototype in Laboratory

Prototype in a Foundry/Fab

"Valley of Death"

Capacity in Production Environment monstration of duction Rates

Defense Program and Commercial Adoption



# **Progression from Concept to Product**

### **Application Platforms**

- Aircraft
- •Ground Systems
- Submarines
- •Missile Defense

Ships

- •C4ISR
- •Space Systems



### S&T

- •Electronic Warfare
- •Secure Edge/IoT Computing
- •AI HW at the Edge
- Quantum Technology
- •5G/6G Technology
- •Commercial Leap Ahead Technologies

### Tech Demos

- RAMP
- •RAMP-C
- •SHIP
- T&AM Prototypes

















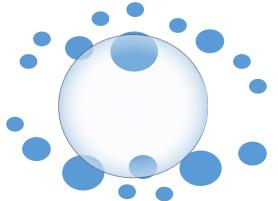
### Hubs

A network of regional entities with lab prototyping capabilities and sources of microelectronics talent for onshore, lab-to-fab transition of semiconductor technologies while ensuring workforce training.

#### Hubs:

- Have the flexibility to bring in members from any region to be successful in their lab-to-fab efforts.
- Connect researchers and designers to prototyping capabilities targeted to strengths in the Hub's technical topic areas.
- Will be centers of expertise for one or more of the six critical technology areas.

#### **Microelectronics Commons**



#### <u>Goal</u>

To connect regional organizations through the Hub to accelerate lab-to-fab prototyping based on proximity and to strengthen local economies through a workforce that supports those regions.

### Cores

Fabs/foundries that have scalable capacity beyond what the regional hubs can provide.

#### Cores serve to:

- Further complement and amplify the work of the regional hubs; for example, ≥200 mm wafer fab for Silicon CMOScompatible technologies and ≥100 mm wafer fab for compound semiconductors.
- Engage with commercial fabs and align them better to commercial processes to facilitate transition to commercial and defense companies.
- Provide access to repeatable processes, back-end manufacturing/integration and full flow-fabrication.



# **Commons Will Support Infrastructure**



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## **Role of Projects**



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### Support

Operational expenditures such as tooling maintenance and staff



### **Facilitate**

Capacity
increase of
existing
infrastructure
through, for
example,
support for
required
staffing

### Build

Additional infrastructure needed for successful prototyping as the Hubs mature



### Develop



Talent and technologies in parallel

## Challenge

Challenges incentivize the collaboration required for Cores to better align Hubs with commercial processes to facilitate transition of technologies.

This enables Hubs to better **support** the broader base of **researchers and designers**.

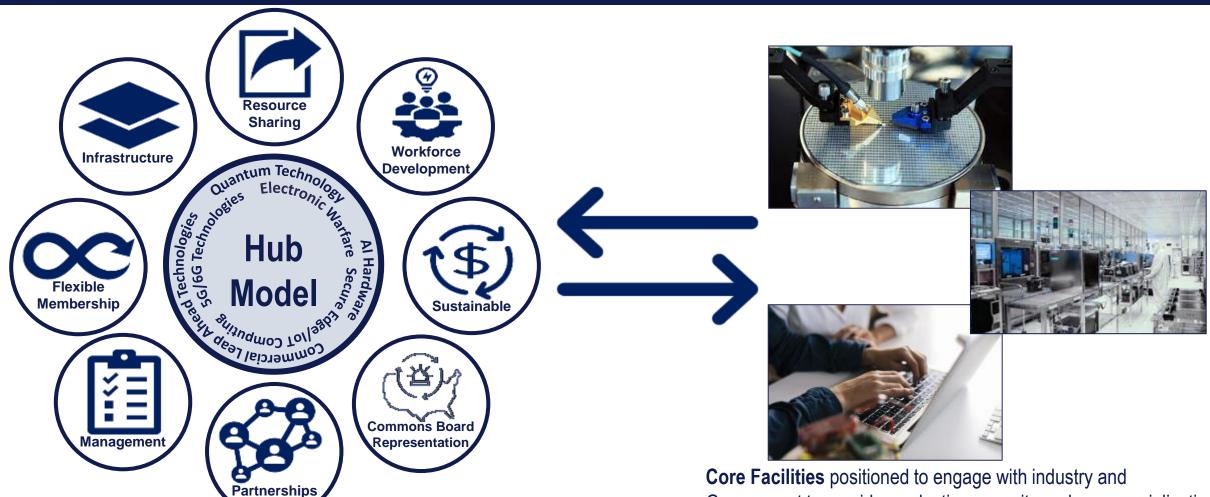




### **Hub Models**



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Government to provide production capacity and commercialization



## **How to Submit your Questions**



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The Naval Surface Warfare Center – Crane (NSWC Crane) Strategic & Spectrum Missions Advanced Resilient Trusted Systems (<u>S<sup>2</sup>MARTS</u>) Other Transaction Authority (OTA) will be the primary contract vehicle for the Microelectronics Commons

The Microelectronics Commons Consortium Manager, the National Security Technology Accelerator (<u>NSTXL</u>), will make program announcements (Events, Documentation changes, etc.) on the S<sup>2</sup>MARTS site and on <u>www.sam.gov</u>

### **Important Links**

- Microelectronics DoD Research & Engineering, OUSD(R&E) (cto.mil): <u>https://www.cto.mil/ct/microelectronics/</u>
- Microelectronics Commons NSTXL: <a href="https://nstxl.org/opportunity/microelectronics-me-commons/">https://nstxl.org/opportunity/microelectronics-me-commons/</a>
  - To submit any questions, locate "Submit a Question" on that site, complete the fields, and click "Submit".